

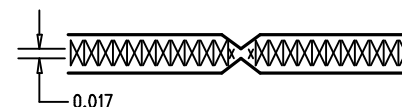
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.035	6	+	PLTD
0.094	6	×	PLTD
0.07	2	□	NPLTD
0.125	4	◇	PLTD
0.015	17	⊗	PLTD

#### NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD  
THICKNESS .062 +/- .006 TOTAL OF 2 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE  
ELECTRODEPOSITED TIN-LEAD COMPOSITION  
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SNOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 <b>LINEAR TECHNOLOGY</b> 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900
	INIT	DATE	
DRAWN			
CHECK			
DESIGN	KIM T.	08-23-02	
ENGR	RAYMOND Z.	08-23-02	<b>TITLE: FABRICATION DRAWING</b> <b>500mA SPREAD-SPECTRUM, LOW NOISE,</b> <b>INDUCTORLESS STEP DOWN DC/DC CONVERTER</b>
SCALE = NONE			SIZE A DEMO DC506A-LTC3251EMSE REV. A DES- 0000 SHT 1 of 1